



INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification ⁷ : B24B 1/00, 37/02, 7/22, 11/00, C09B 3/14	A1	(11) International Publication Number: WO 00/43159 (43) International Publication Date: 27 July 2000 (27.07.00)
(21) International Application Number: PCT/US00/01495 (22) International Filing Date: 21 January 2000 (21.01.00) (30) Priority Data: 60/116,547 21 January 1999 (21.01.99) US (71) Applicant: RODEL HOLDINGS, INC. [US/US]; Suite 1300, 1105 North Market Street, Wilmington, DE 19899 (US). (72) Inventors: JAMES, David, B.; 221 Aronimink Drive, Newark, DE 19711 (US). COOK, Lee, Melbourne; 20 Bryson Road, Steelville, PA 19310 (US). BAKER, Arthur, Richard; 404 Ramsey Road, Wilmington, DE 19803 (US). (74) Agent: BENSON, Kenneth, A.; Rodel Holdings, Inc., Suite 1300, 1105 North Market Street, Wilmington, DE 19899 (US).		(81) Designated States: CN, JP, KR, SG; European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: IMPROVED POLISHING PADS AND METHODS RELATING THERETO (57) Abstract This invention describes improved polishing pads useful in the manufacture of semiconductor devices or the like. The pads of the present invention have an advantageous hydrophilic polishing material and are sufficiently thin to generally improve predictability and polishing performance.		